Title (en)

Lead-free copper alloy and use thereof

Title (de)

Bleifreie Kupferlegierung und deren Verwendung

Title (fr)

Alliage de cuivre sans plomb et son utilisation

Publication

EP 1452613 A3 20040922 (DE)

Application

EP 04002009 A 20040130

Priority

DE 10308778 A 20030228

Abstract (en)

[origin: EP1452613A2] The Cu-Zn-Si based alloy comprises in wt%: Cu 70-83, Si 1-5. The following matrix-active elements are also included: Sn 0.01-2, Fe and/or Co 0.01-3, Ni 0.01-0.3, Mn 0.01-0.3, P up to 0.1 (optional), and up to 0.5% of Ag, Al , As, Mg, Sb, Ti, Zr. The remainder is Zn, with inevitable impurities.

IPC 1-7

C22C 9/10

IPC 8 full level

C22C 9/04 (2006.01); **C22C 9/10** (2006.01)

CPC (source: EP US)

C22C 9/04 (2013.01 - EP US); **C22C 9/10** (2013.01 - EP US)

Citation (search report)

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DOCDB simple family (publication)

EP 1452613 A2 20040901; **EP 1452613 A3 20040922**; **EP 1452613 B1 20071205**; AT E380258 T1 20071215; AU 2004200784 A1 20040916; AU 2004200784 B2 20090820; CA 2458723 A1 20040828; CA 2458723 C 20091006; CN 100430498 C 20081105; CN 1524970 A 20040901; DE 10308778 B3 20040812; DE 502004005634 D1 20080117; DK 1452613 T3 20080414; JP 2004263301 A 20040924; JP 4537728 B2 20100908; US 2004234411 A1 20041125; US 7354489 B2 20080408

DOCDB simple family (application)

EP 04002009 A 20040130; AT 04002009 T 20040130; AU 2004200784 A 20040227; CA 2458723 A 20040225; CN 200410004293 A 20040218; DE 10308778 A 20030228; DE 502004005634 T 20040130; DK 04002009 T 20040130; JP 2004041154 A 20040218; US 78803704 A 20040226